

Nicholas R Jankowski

List of Publications by Year in descending order

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28
papers

704
citations

1040056

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h-index

1372567

10
g-index

28
all docs

28
docs citations

28
times ranked

697
citing authors

#	ARTICLE	IF	CITATIONS
1	A review of phase change materials for vehicle component thermal buffering. Applied Energy, 2014, 113, 1525-1561.	10.1	343
2	Two-Phase Thermal Ground Planes: Technology Development and Parametric Results. Journal of Electronic Packaging, Transactions of the ASME, 2015, 137, .	1.8	59
3	Numerical investigation and sensitivity analysis of manifold microchannel coolers. International Journal of Heat and Mass Transfer, 2012, 55, 7698-7708.	4.8	57
4	Thermal performance of a flat polymer heat pipe heat spreader under high acceleration. Journal of Micromechanics and Microengineering, 2012, 22, 045018.	2.6	53
5	Experimental evaluation of metallic phase change materials for thermal transient mitigation. International Journal of Heat and Mass Transfer, 2018, 116, 512-519.	4.8	52
6	Wireless Power Transmission via Modulated Laser Irradiation of Pyroelectric Thin Films. Advanced Materials Technologies, 2016, 1, 1600178.	5.8	15
7	Measurement of High-Performance Thermal Interfaces Using a Reduced Scale Steady-State Tester and Infrared Microscopy. Journal of Heat Transfer, 2016, 138, .	2.1	14
8	Thermodynamic cycle optimization for pyroelectric energy conversion in the thin film regime. International Journal of Energy Research, 2017, 41, 1880-1890.	4.5	14
9	Electrical Supercooling Mitigation in Erythritol. , 2010, , .		11
10	The Impact of GaN/Substrate Thermal Boundary Resistance on a HEMT Device. , 2011, , .		11
11	Comparing Microchannel Technologies to Minimize the Thermal Stack and Improve Thermal Performance in Hybrid Electric Vehicles. , 2007, , .		10
12	Stereolithographically fabricated aluminum nitride microchannel substrates for integrated power electronics cooling. Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, 2008, , .	0.0	9
13	GaN HEMT Junction Temperature Dependence on Diamond Substrate Anisotropy and Thermal Boundary Resistance. , 2012, , .		7
14	Numerical Evaluation of Multiple Phase Change Materials for Pulsed Electronics Applications. , 2016, , .		6
15	Kapitza Resistance at the Two-Dimensional Electron Gas Interface. , 2019, , .		6
16	A Micromachined Manifold Microchannel Cooler. , 2009, , .		5
17	Thermal performance of a Direct-Bond-Copper Aluminum Nitride manifold-microchannel cooler. , 2010, , .		5
18	Experimental Investigation of a Flat-Plate Oscillating Heat Pipe During High-Gravity Loading. , 2011, , .		5

#	ARTICLE	IF	CITATIONS
19	Two-Phase Minichannel Cold Plate for Army Vehicle Power Electronics. , 2011, , .		4
20	Voiding Effects on the Thermal Response of Metallic Phase Change Materials Under Pulsed Power Loading. , 2017, , .		4
21	Nonintrusive Optical Validation of Two-Phase Flow Regimes in a Small-Diameter Tube. Heat Transfer Engineering, 2016, 37, 972-984.	1.9	3
22	Modified Model for Improved Flow Regime Prediction in Internally-Grooved Tubes. , 2013, , .		2
23	Analysis and Characterization of Thermal Expansion-Matched Wick-Based Multi-Chip Passive Heat Spreaders in Static and Dynamic Environments. , 2013, , .		2
24	Non-Intrusive Optical Validation of Two-Phase Flow Regimes in a Small Diameter Tube. , 2014, , .		2
25	Thermal Model of a Thin Film Pulsed Pyroelectric Generator. , 2016, , .		2
26	Design and Fabrication of a Substrate Integrated Phase Change Thermal Buffer Heat Sink. , 2009, , .		1
27	Interfacial Resistance Measurement of High Performance Thermal Interface Materials. , 2013, , .		1
28	Numerical Study on the Thermal Performance of a Substrate Integrated Thermal Buffer Heat Sink. , 2011, , .		1